



# SMOOTH N SLEEK SDN BHD

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## BENEFITS

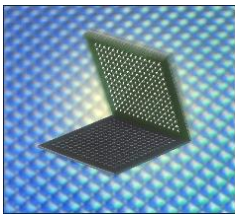
This patent pending EZReball™ reballing preform consists of an array of solder spheres positioned with a high temperature polyimide stencil and an adhesive-backed carrier with custom engineered adhesive to hold the solder balls in place. The preforms can be made quickly without tooling charges in almost any possible array pattern, including various solder alloys, pitches and ball diameters.

EZReball™ BGA Preforms will accurately place a new array of solder balls relying on simple physical properties rather than operator skill. These preforms place the solder balls to within a xxmm tolerance. The preform process relies on edge registration so that the user “squares up” the preform with the package being reballed.

Unlike other processes, the EZReball™ process is faster and simpler as paper remnants do not need to be cleaned from the surface.

We package it better than the competition. That means you get more usable preforms instead of preforms that have had the balls knocked out during shipping.

It's not unusual with any reball process to occasionally have one or two balls not adhered to BGA after processing. That's why we've included our repair stencil. It is used when there is a need to replace only a few balls.



## Why EZReball™ Preforms Over Stencil Methods Involving Loose Solder Spheres or Solder Paste?

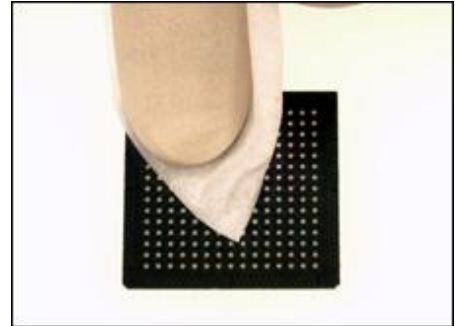
Using other stencil methods using loose solder spheres, you can typically process only one component at a time. Using the EZReball™ preforms, you can process many parts at the same

time with only a few minutes of extra labor. Based on our time studies if you have to reball 10 or more devices the EZReball™ method is at least 30% faster!

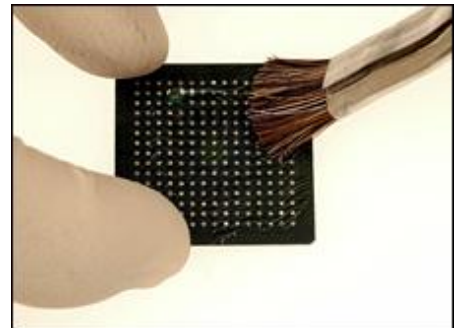
Small volume ball attach methods using stencils generally require you to have a different stencil for all of your different array patterns, which gets very expensive. We can process your EZReball™ stencil using our LASER machining capabilities eliminating the need for mechanical fixturing which is expensive and takes time to manufacture. There are no tooling costs associated with any new EZReball™ patterns ordered.

EZReball™ reballing preforms are designed to work with your existing tools and equipment. You can use any adequate reflow system (BGA rework system, oven, etc) you have.

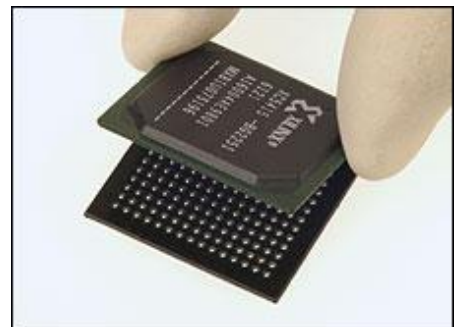
## EZReball™ SPEEDS DEVICE REBALLING!



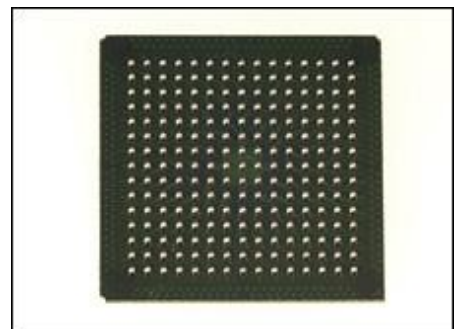
1. Dress Site and Clean



2. Apply Paste Flux



3. Align and Place BGA on to Preform



4. Post Reflow and Preform Removal